

ABSTRACT OF THE DISCLOSURE

An apparatus incorporating small-feature size and large-feature-size components. The apparatus comprise a strap including a substrate with an integrated circuit contained therein. The integrated circuit coupling to a first conductor disposed on the substrate. The first conductor is made of a thermosetting or a thermoplastic material including conductive fillers. A large-scale component having a second conductor is electrically coupled to the first conductor to electrically couple the large-scale component to the integrated circuit. The large-scale component includes a second substrate.